What is claimed is:

1. A manufacturing method for an organic EL display which is provided with an organic EL element and a semiconductor element which drives the organic EL element on a display base board,

the manufacturing method for an organic EL display comprising the step of disposing a unit block having said semiconductor element at a predetermined position of a display base board.

2. Manufacturing method for an organic EL display according to claim 1 the unit block being formed such that said plural semiconductor elements are formed on a single crystal semiconductor base board in parallel, and this base board is divided.

3. Manufacturing method for an organic EL display according to claim 1 a concavity having a shape corresponding to the shape of the unit block being formed at a predetermined position of base board of display, the unit block being disposed at a predetermined position of the display base board by fitting unit block into this concavity in a liquid.

4. Manufacturing method for an organic EL display according to claim 1 by arranging a hole which penetrates in the thickness direction through the display base board in a predetermined position of the display base board, and by introducing the unit block to the position of said hole on one surface of display base board by making the pressure at one face of the display base board greater than the pressure at the other face, or by drawing the liquid into said hole, the unit block being disposed at a predetermined position of the

display base board.

5. Manufacturing method for an organic EL display according to claim 4 wiring being performed by using said hole.

6. Manufacturing method for an organic EL display according to claim 1 the unit block being introduced to be disposed at a predetermined position of the display base board by Coulomb attractive force.

7. Manufacturing method for an organic EL display according to claim 1 characterized in disposing materials for an organic EL element corresponding to the position of a pixel on display base board by an ink jet method.

8. Manufacturing method for an organic EL display according to claim 1 characterized in forming wiring which is formed on display base board by an ink jet method.

9. Manufacturing method for an organic EL display according to claim 1 driving method being active-matrix method.

10. Manufacturing method for an organic EL display according to claim 9 scanning line, signal line, and power supply line terminals for connecting wiring inside the unit block of these wirings being formed on the display base board in advance, after terminals for connecting wirings on the display base board being formed at the position which contacts these terminals at the time of disposing on the display base board in the unit block, the unit block being disposed at a predetermined position on the display base board.

11. Manufacturing method for an organic EL display according to claim 9 the unit block having plural semiconductor elements for driving plural neighboring organic EL elements.

12. Manufacturing method for an organic EL display according to claim 11 plural elements for each organic EL element being disposed such that the planar shape of the unit block is polygonal and is rotationally symmetrical centered at the center of the polygon.

13. Manufacturing method for an organic EL display according to claim 11 the planar shape of the unit block being rectangular, and plural terminals for each organic EL element being disposed so as to be axisymmetric with respect to center lines which are parallel with the longer side of the rectangle and the center line which is parallel to the shorter side of the rectangle.

14. Manufacturing method for an organic EL display according to claim 11 planar shape of the unit block being polygonal, and plural terminals for each organic EL element being disposed along each diagonal line of the polygon, and the position of the terminals on each of the diagonal lines being such that the same terminal is on the same previous position after the rotation.

15. Manufacturing method for an organic EL display according to claim 12 said polygon being an equilateral polygon.

16. Manufacturing method for an organic EL display according to claim 14 said polygon being an equilateral polygon.

17. Manufacturing method for an organic EL display according to claim 11 plural groups of organic EL element made of 3 pieces of neighboring organic EL elements such as red color light emitting, blue color light emitting, green color light emitting being disposed on display base board, unit block having semiconductor element for driving 3 pieces of organic EL elements being disposed at the position which is center of 3 pieces of organic EL element per each group.

18. Manufacturing method for an organic EL display according to claim 11 plural groups of organic EL element made of each 6 pieces of neighboring organic EL elements such as 2 pieces of red color light emitting, 2 pieces of blue color light emitting, 2 pieces of green color light emitting being disposed on display base board, unit block having semiconductor element for driving 6 pieces of organic EL elements being disposed at the position which is center of 6 pieces of organic EL element per each group.

19. A disposing method for a semiconductor element in which a unit block having a semiconductor element is disposed at a predetermined position on a base board,

the disposing method for a semiconductor element characterized in that by arranging a hole which penetrates in the thickness direction through a display base board at a predetermined position of the display base board, and by making the pressure at one face of the display base board higher than the pressure at the other face, or by drawing the liquid into said hole so as to introduce unit block at the position of said hole on one surface of display base board.

20. A disposing method for a semiconductor element in which a unit block having a semiconductor element is disposed at a predetermined position on a base board,

disposing method for a semiconductor element characterized in that the unit block is introduced at a predetermined position on the base board by Coulomb attractive force.

21. A manufacturing method for a semiconductor device in which a unit block having semiconductor element is disposed at a predetermined position on a base board,

the manufacturing method for a semiconductor device wherein the wiring which is formed on a base board being formed by an ink jet method.

22. A manufacturing method for a semiconductor device having a process in which a unit block having semiconductor element is disposed at a predetermined position on a base board,

the manufacturing method for a semiconductor device the wiring and terminals for connecting with wiring inside the unit block of this wiring being formed on a base board in advance, in the unit block, at a position which contacts terminals on the base board at the time of disposing on the base board, after the terminal for connecting with the wiring on the base board being formed in advance in the unit block, and the unit block being disposed at a predetermined position on the base board.

23. A manufacturing method for a semiconductor device having process in which a unit block having plural semiconductor elements is disposed at a predetermined position of the base board,

the manufacturing method for a semiconductor device which disposes plural terminals for each semiconductor element such that the planar shape of the unit block is polygonal, and the rotation symmetricalness is centered by the center of this polygon.

24. A manufacturing method for a semiconductor device having a process in which a unit block having plural semiconductor elements is disposed at a predetermined position on a base board,

the manufacturing method for a semiconductor device in which plural terminals for each semiconductor element are disposed such that plan view of the unit block is made rectangular, and plural terminals for each organic EL elements are disposed so as to be axisymmetric relative to both center lines which are parallel with the longer side of the rectangle and center line which is parallel to the shorter side of the rectangle.

25. A manufacturing method for a semiconductor device having a process in which a unit block having plural semiconductor elements is disposed at a predetermined position on a base board,

the manufacturing method for a semiconductor device the plan view of unit block being polygonal, and plural terminals for each semiconductor element being disposed along each diagonal line of this polygon, and the position of the terminals on each diagonal line being such that the same terminal is on the same previous position after the rotation.

26. A manufacturing method for an organic EL display according to claim 23 said polygon being an equilateral polygon.

27. A manufacturing method for an organic EL display according to claim 25 said polygon being an equilateral polygon.

28. A manufacturing method for an active-matrix type organic EL display a light emitting layer which is inserted among at least two pieces of electrode per pixel and said light emitting layer being driven by a semiconductor element,

the manufacturing method for an active-matrix type organic EL display characterized in that the semiconductor element is formed on a base board, said semiconductor element is detached from the base board so as to be divided per unit blocks, said unit blocks of said semiconductor element is disposed on other base board.

29. A manufacturing method for an electro-optic device which is provided with an electro-optic element and a semiconductor element which drives this electro-optic element on a display base board,

the manufacturing method for electro-optic device comprising a process which disposes a unit block having said semiconductor element at a predetermined position of the display base board.

30. An electro-optic device which is provided with an electro-optic element and a semiconductor element which drives this electro-optic element on a display base board,

the electro-optic device characterized in that a unit block which is provided with driving circuit having said semiconductor element is disposed at a predetermined position on the display base board.

31. An electro-optic device according to claim 30 plural terminals for each

electro-optic element being disposed at said unit block such that the rotational symmetry is centered at the center in plan view of said unit block.

32. An electronic device having an electro-optic device according to claim 30.

33. An electronic device having an electro-optic device according to claim 31.